

HVM**

Features

Controlled avalanche characteristic combined with the ability to dissipate reverse power
 Plastic package has underwriters laboratory lammability classification 94V-0
 Low forward voltage drop
 Typical IR less than 1 uA
 High overload surge capability
 High temperature soldering guaranteed
 260-C/10s/.375" (9.5mm) lead length at 5 lbs., (2.3kg) tension



Mechanical data

Case: Reliable low cost construction utilizing molded plastic technique
Terminals: Axial leads. Solderable per MIL-STD-202 Method 208
Polarity: Color band denotes cathode end
Weight: 2.6 g

We declare that the material of product compliance with RoHS requirements.

1.Electrical Characteristic

Maximum Ratings & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	HVM5	HVM8	HVM10	HVM12	HVM15	HVM16	HVM18	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	5	8	10	12	15	16	18	KV
Maximum RMS voltage	V_{RMS}	3.5	5.6	7	8.4	10.5	11.2	12.6	KV
Maximum DC blocking voltage	V_{DC}	5	8	10	12	15	16	18	KV
Maximum average forward rectified current 0.375" (9.5mm) lead length at TA=55-C	I_o	450							mA
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Operating junction and storage temperature range	T_J, T_{STG}	-40 to +130							-C

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	HVM5	HVM8	HVM10	HVM12	HVM15	HVM16	HVM18	Unit
Maximum instantaneous forward voltage at 1A	V _F	10.0		12		14		16	V
Maximum DC reverse current at rated DC blocking voltage TA=25-C	I _R	10.0							μA

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2.Ratings and Characteristic Curves(TA= 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

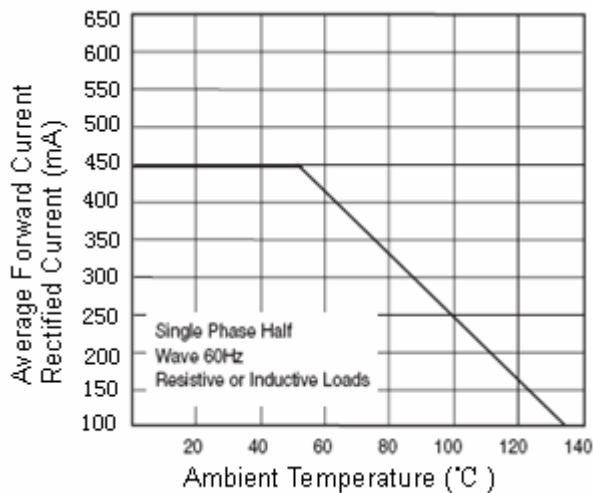


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

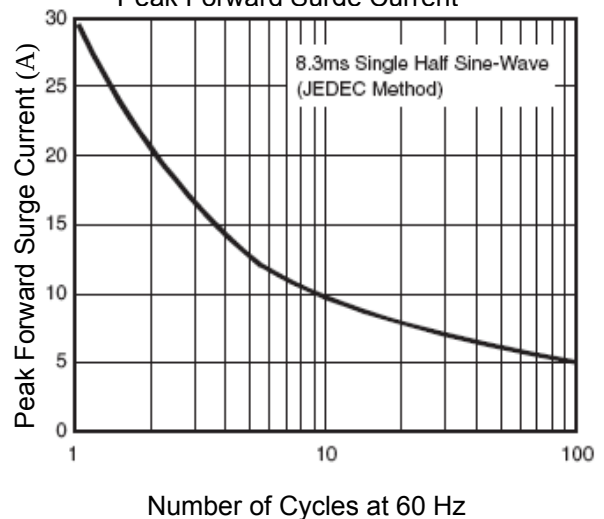


Fig. 3 - Typical Reverse Characteristics

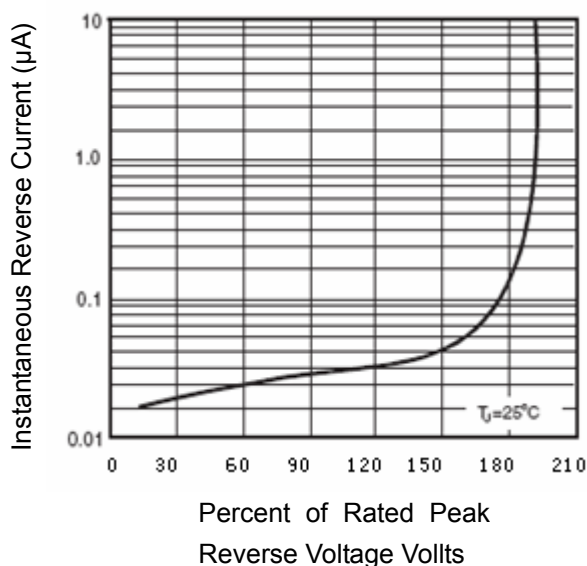
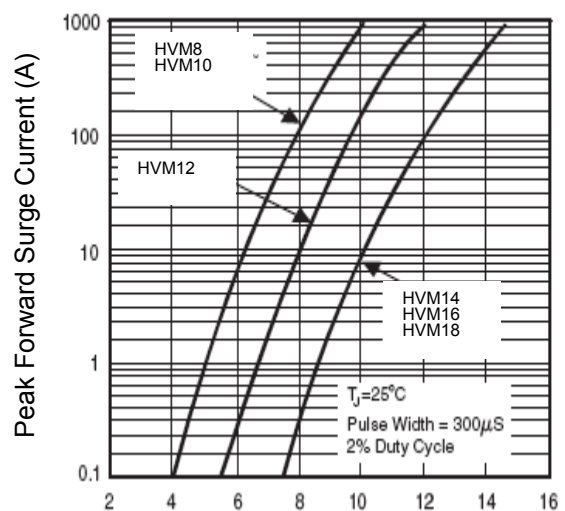
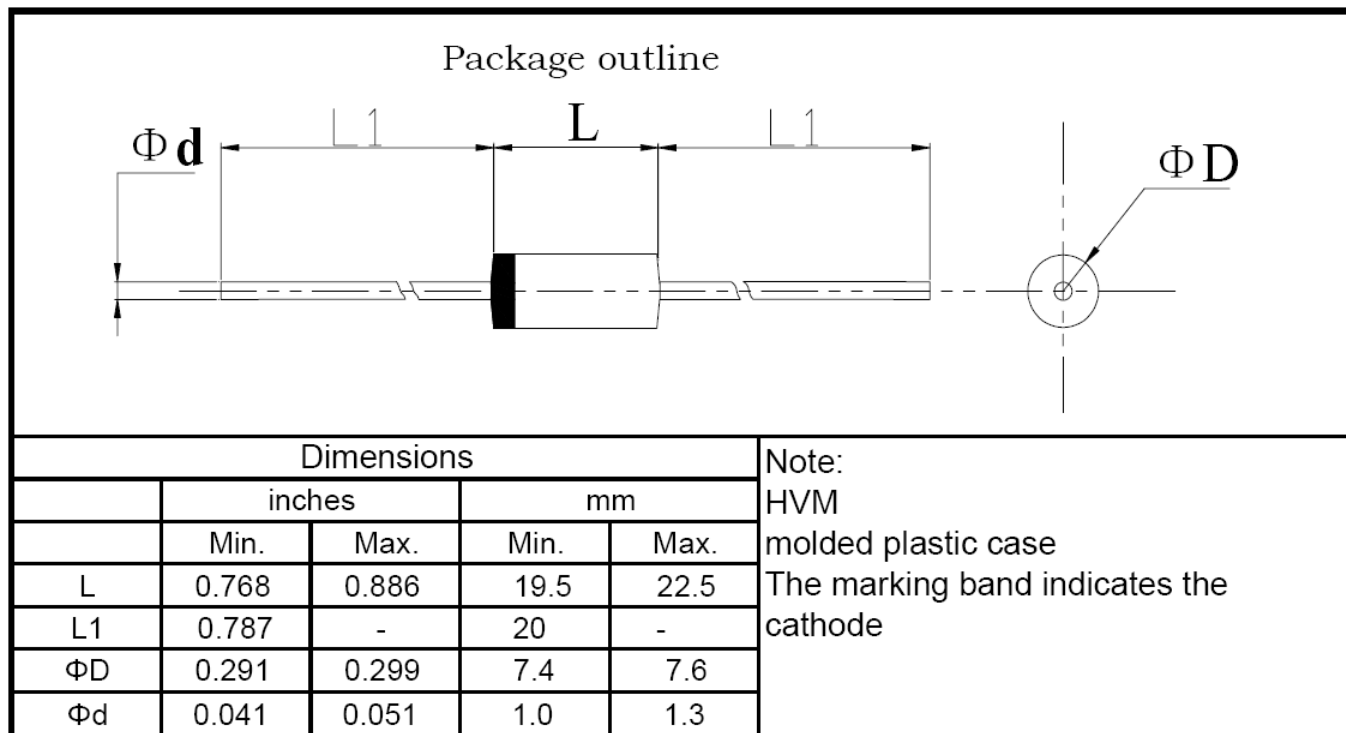


Fig.4-Typical Instantaneous Forward Characteristics



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3. dimension:



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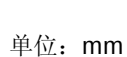
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塑料袋规格:

110 150mm

材料：单瓦楞纸



LRC标签

成型规格

LRC产品

二、产品重复峰

产品额定电

—产品数量

产品生产日

塑封生产线高压硅堆产品包装规范

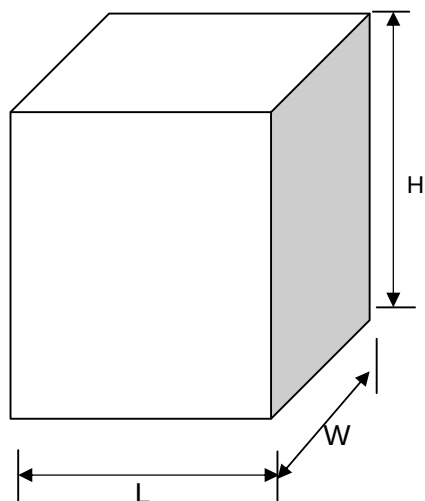
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5.1.3 外箱

材料: 双瓦楞纸



单位: mm

	L	W	H
尺寸	475±2	335±2	380±4

5.2. 包装数量

5.2.1

袋装要求:

每个塑料袋内装50PCS不打端子的高压硅堆或双向二极管、一张合格证、一袋干燥剂;

每个塑料袋内装20PCS打端子的高压硅堆或双向二极管、一张合格证、一袋干燥剂;

5.2.2

盒装要求:

每盒装16代不打端子的高压硅堆或双向二极管

每盒装25代打端子的高压硅堆或双向二极管

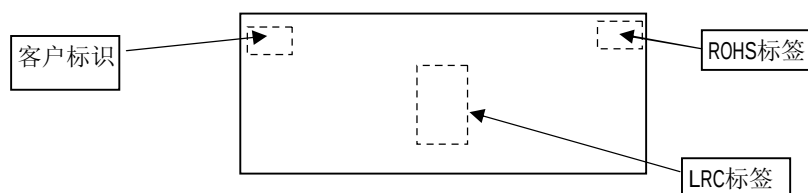
5.2.3

外箱要求:

每箱装10个内盒

5.2.4

标签要求:



塑封生产线高压硅堆产品包装规范

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5.3 产品出厂检验报告

每批出货时, 需要附上出厂检验报告

5.4 环保标签:



5.5. 无卤 (无卤产品才贴)



塑封生产线高压硅堆产品包装规范

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6、版式次更新记录

版次	更新记录	更新作者	更新日期
1	第一版	余波	2011年9月28日

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4.Update Record

版次	更新记录	更新作者	更新日期
1	第一版	余波	2010-5-25